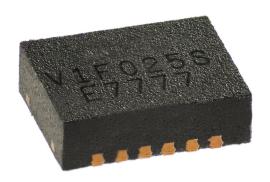


# CGHV1F025S

25 W, DC - 15 GHz, 40 V, GaN HEMT

#### **Description**

The CGHV1F025S is an unmatched, gallium nitride (GaN) high electron mobility transistor (HEMT) designed specifically for high efficiency, high gain and wide bandwidth capabilities. The device can be deployed for L-, S-, C-, X- and Ku-Band amplifier applications. The datasheet specifications are based on a X-Band (8.9 -9.6 GHz) amplifier. The CGHV1F025S operates on a 40 volt rail circuit while housed in a 3mm x 4mm, surface mount, dual-flat-no-lead (DFN) package. Under reduced power, the transistor can operate below 40V to as low as 20V VDD, maintaining high gain and efficiency.



Package Type: 3x4 DFN PN: CGHV1F025S

### Typical Performance 8.9 - 9.6 GHz ( $T_c = 25$ °C), 40 V

Parameter	8.9 GHz	9.2 GHz	9.4 GHz	9.6 GHz	Units
Output Power @ P <sub>IN</sub> = 37 dBm	24	29	27	25	W
Drain Efficiency @ P <sub>IN</sub> = 37 dBm	43.5	48.5	48	46	%
Gain @ P <sub>IN</sub> = 0 dBm	10.7	11.6	11.3	11.1	dB

Measured in the CGHV1F025S-AMP1 application circuit. Pulsed 100µs 10% duty

#### **Features**

- Up to 15 GHz Operation
- 25 W Typical Output Power
- 11 dB Gain at 9.4 GHz
- Application circuit for 8.9 9.6 GHz







#### Absolute Maximum Ratings (not simultaneous) at 25°C

Parameter	Symbol	Rating	Units	Conditions
Drain-Source Voltage	V <sub>DSS</sub>	120	V	25°C
Gate-to-Source Voltage	V <sub>GS</sub>	-10, +2	V	25°C
Storage Temperature	T <sub>STG</sub>	-65, +150	°C	
Operating Junction Temperature	TJ	225		
Maximum Forward Gate Current	I <sub>GMAX</sub>	4.8	mA	3500
Maximum Drain Current <sup>1</sup>	I <sub>DMAX</sub>	2	А	- 25°C
Soldering Temperature <sup>2</sup>	Ts	245	0.0	
Case Operating Temperature <sup>3,4</sup>	T <sub>C</sub>	-40, +150	°C	
Thermal Resistance, Junction to Case⁵	$R_{\theta JC}$	3.4	°C/W	85°C

#### Notes:

#### **Electrical Characteristics**

Characteristics	Symbol	Min.	Тур.	Max.	Units	Conditions	
DC Characteristics <sup>1</sup>							
Gate Threshold Voltage	$V_{GS(th)}$	-3.8	-3.0	-2.3	V	$V_{DS} = 10 \text{ V}, I_{D} = 4.8 \text{ mA}$	
Gate Quiescent Voltage	$V_{GS(Q)}$	_	-2.7	_	V <sub>DC</sub>	V <sub>DS</sub> = 40 V, I <sub>D</sub> = 120 mA	
Saturated Drain Current <sup>2</sup>	I <sub>DS</sub>	3.5	4.8	_	Α	$V_{DS} = 6.0 \text{ V}, V_{GS} = 2.0 \text{ V}$	
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	100	_		$V_{DC}$	$V_{GS} = -8 \text{ V}, I_D = 4.8 \text{ mA}$	
RF Characteristics $^3$ ( $T_c = 25$ $^\circ$ C, $F_0 = 5.55$ GHz unless otherwise noted)							
Gain	G	-	15.1	-	dB	$V_{DD} = 40 \text{ V}, I_{DQ} = 120 \text{ mA}, P_{IN} = 10 \text{ dBm}$	
Output Power <sup>4</sup>	Роит	_	44.8	_	dBm	V 40VI 100 A B 20 F IB	
Drain Efficiency⁴	η	_	51	_	%	$V_{DD} = 40 \text{ V}, I_{DQ} = 120 \text{ mA}, P_{IN} = 33.5 \text{ dBm}$	
Output Mismatch Stress <sup>4</sup>	VSWR	-	_	10:1	Ψ	No damage at all phase angles, $V_{DD} = 40 \text{ V}, I_{DQ} = 120 \text{ mA}, P_{IN} = 33.5 \text{ dBm}$	
Dynamic Characteristics							
Input Capacitance	C <sub>GS</sub>	-	5.9	-			
Output Capacitance	C <sub>DS</sub>	_	2	_	pF	$V_{DS} = 40 \text{ V}, V_{GS} = -8 \text{ V}, f = 1 \text{ MHz}$	
Feedback Capacitance	C <sub>GD</sub>	_	0.21	_			

#### Notes

- <sup>1</sup> Measured on wafer prior to packaging
- <sup>2</sup> Scaled from PCM data
- <sup>3</sup> Measured in production test fixture.
- $^4$  Pulsed 100µs, 10% duty cycle
- <sup>5</sup> Includes package

<sup>&</sup>lt;sup>1</sup> Current limit for long term, reliable operation

<sup>&</sup>lt;sup>2</sup> Refer to the Application Note on soldering

<sup>&</sup>lt;sup>3</sup> Simulated at P<sub>DISS</sub> = 24 W

<sup>&</sup>lt;sup>4</sup> T<sub>c</sub> = Case temperature for the device. It refers to the temperature at the ground tab underneath the package. The PCB will add additional thermal resistance

<sup>&</sup>lt;sup>5</sup> Pulsed (100µs, 10% Duty). Rth for the reference design using a 10 mil Rogers 5880 PCB with 31 (Ø13 mil) Vias would be 3.6°C/W. For CW operation the Rth numbers increase to 5°C/W for just the device, and 7.3°C/W including the board

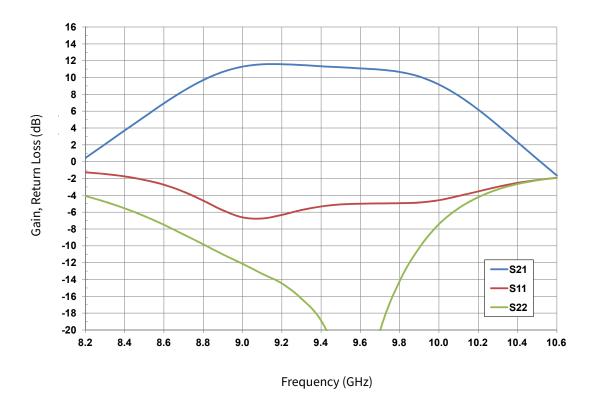


#### **Electrical Characteristics When Tested in CGHV1F025S-AMP1**

Characteristics	Symbol	Тур.	Max.	Units	Conditions	
RF Characteristics¹ (T <sub>c</sub> = 25°C, F <sub>o</sub> = 8.9 - 9.6 GHz unless otherwise noted)						
Gain	G	11.6	_	dB	$V_{DD} = 40 \text{ V}, I_{DQ} = 150 \text{ mA}, P_{IN} = 0 \text{ dBm}$	
Output Power <sup>2</sup>	P <sub>out</sub>	29	-	W	$V_{DD} = 40 \text{ V}, I_{DQ} = 150 \text{ mA}, P_{IN} = 37 \text{ dBm}$	
Drain Efficiency <sup>2</sup>	η	48.5	_	%		
Output Mismatch Stress <sup>2</sup>	VSWR	_	10:1	Ψ	V <sub>DS</sub> = 40 V, V <sub>GS</sub> = -8 V, P <sub>OUT</sub> = 25 W	

#### Notes:

#### **Typical Performance - CGHV1F025S**



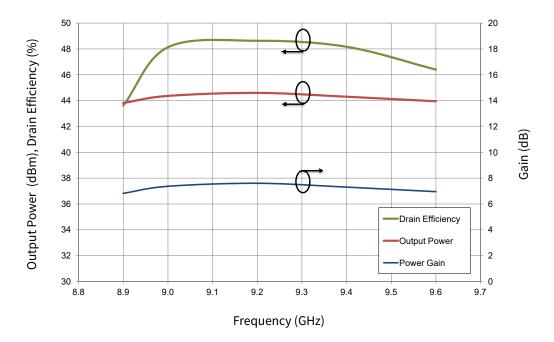
**Figure 1.** Typical Small Signal Response of CGHV1F025S-AMP1 Application Circuit  $V_{DD}$  = 40 V,  $I_{DQ}$  = 150 mA

<sup>&</sup>lt;sup>1</sup> Measured in CGHV1F025S-AMP1 Application Circuit

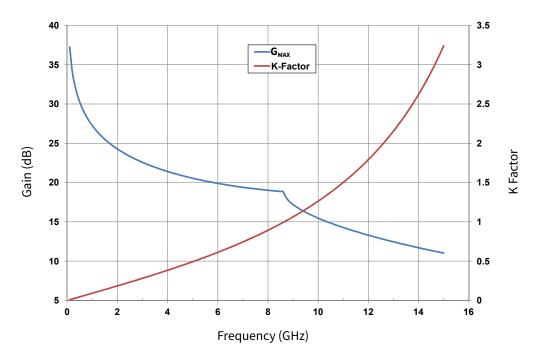
<sup>&</sup>lt;sup>2</sup> Pulsed 100μs, 10% duty cycle



### Typical Performance in Application Circuit CGHV1F025S-AMP1



**Figure 2.** Typical Large Signal Response  $V_{DD}$  = 40 V,  $I_{DQ}$  = 150 mA,  $P_{IN}$  = 37 dBm  $T_{CASE}$  = 25°C, Pulse Width = 100 $\mu$ s, Duty Cycle = 10%



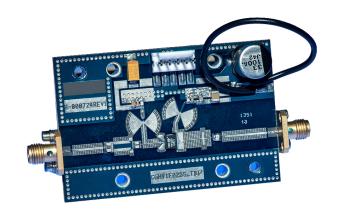
**Figure 3.**  $G_{MAX}$  and K-Factor vs Frequency  $V_{DD} = 40 \text{ V}$ ,  $I_{DO} = 150 \text{ mA}$ ,  $T_{CASE} = 25^{\circ}\text{C}$ 



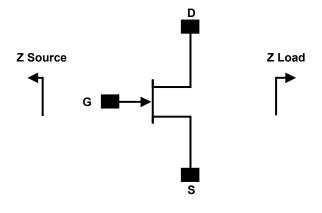
#### CGHV1F025S-AMP1 Application Circuit Bill of Material

### CGHV1F025S-AMP1 Application Circuit

Designator	Description	Qty
R1	RES, 100, OHM, +1/-1%, 1/16 W, 0603	2
R2	RES, 10, OHM, +1/-1%, 1/16 W, 0603	1
C1, C2	CAP, 1pF, ±0.1pF, 0603, ATC	3
C3, C4	CAP, 1.8pF, ±0.1pF, 0603, ATC	3
C9, C10	CAP, 0.6pF, ±0.1pF, 0603, ATC	1
C5, C11	CAP, 10pF, ±5%, 0603, ATC	1
C6, C12	CAP, 470pF, 5%, 100 V, 0603, X	2
C7, C13	CAP, 33000pF, 0805, 100V, X7R	1
C14	CAP, 1.0μF, 100V, 10%, X7R, 1210	3
C8	CAP, 10μF, 16V TANTALUM	3
C15	CAP, 33μF, 20%, G CASE	1
J1, J2	CONN, SMA, PANEL MOUNT JACK, FLANGE	1
J3	HEADER RT>PLZ .1CEN LK 5POS	2
Q1	QFN TRANSISTOR CGHV1F025S	1
W1	CABLE, 18 AWG, 4.2	1



### Source and Load Impedances



Frequency (GHz)	Z Source	Z Load
8.00	1.16 - j12.0	4.33 - j3.47
8.25	1.12 - j12.92	4.20 - j4.34
8.50	0.96 - j13.39	3.37 - j5.23
8.75	1.07 - j14.33	3.50 - j6.11
9.00	1.06 - j14.80	3.45 - j6.99
9.25	1.15 - j15.76	3.38 - j7.44
9.50	1.17 - j16.24	3.31 - j7.89
9.75	1.14 - j17.21	3.25 - j8.78
10.00	1.30 - j17.70	3.21 - j9.23



### **Electrostatic Discharge (ESD) Classifications**

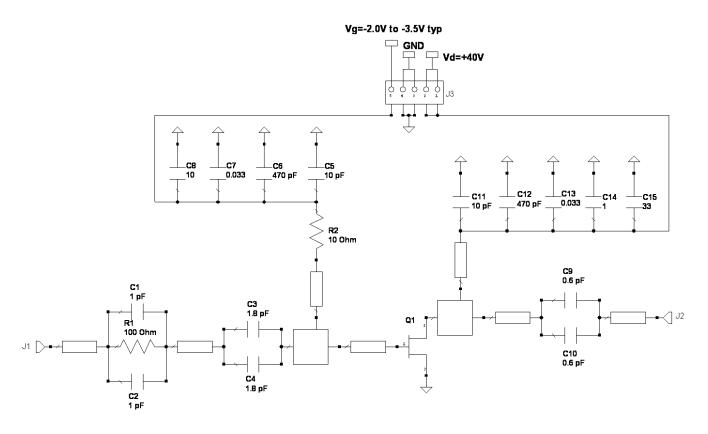
Parameter	Symbol	Class	Classification Level	Test Methodology
Human Body Model	НВМ	1A	ANSI/ESDA/JEDEC JS-001 Table 3	JEDEC JESD22 A114-D
Charge Device Model	CDM	С3	ANSI/ESDA/JEDEC JS-002 Table 3	JEDEC JESD22 C101-C

### Moisture Sensitivity Level (MSL) Classification

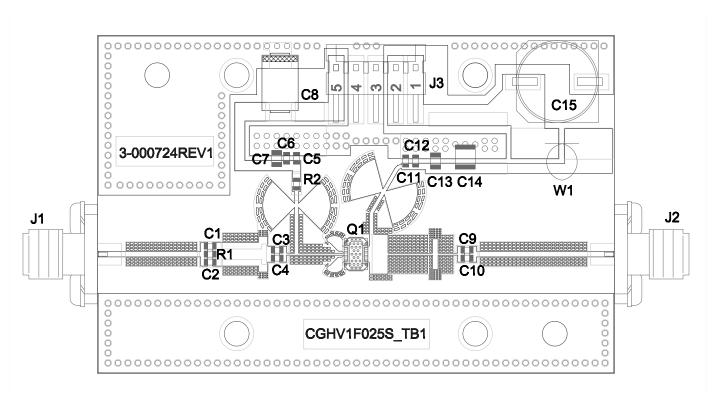
Parameter	Symbol	Level	Test Methodology
Moisture Sensitivity Level	MSL	3 (168 hours)	IPC/JEDEC J-STD-20



#### **CGHV1F025S-AMP1 Application Circuit Schematic**



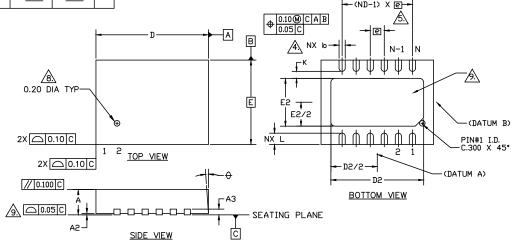
### **CGHV1F025S-AMP1 Application Circuit Outline**



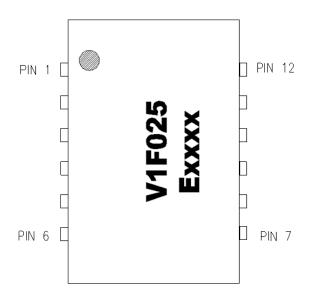


### Product Dimensions CGHV1F025S (Package 3 x 4 DFN)

S-MBOL	СОММО	N <sub>O</sub>				
٥	MIN.	NOM.	MAX.	NOTE		
Α	0.80	0.90	1.0			
Α1	0.00	0.02	0.05			
A3	(	0.203 REF				
Φ	0		12	2		
D	4.00 BSC					
Ε	3.00 BSC					
e	0.50 BSC					
N	12					
ND		6		_ ゑ		
L	0.35	0.40	0.45			
Ф	0.18	0.25	0.30	<u> </u>		
D2	3.20	3.30	3.40			
E2	1.60	1.7	1.80			
K	0.20					



Frequency	Z Source
1	GND
2	RF IN
3	RF IN
4	RF IN
5	RF IN
6	GND
7	GND
8	RF OUT
9	RF OUT
10	RF OUT
11	RF OUT
12	GND



Note: Leadframe finish for 3x4 DFN package is Nickel/Palladium/Gold. Gold is the outer layer



#### **Part Number System**

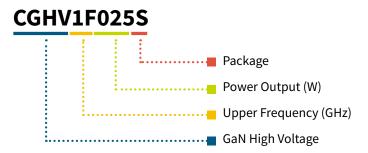


Table 1.

Parameter	Value	Units
Upper Frequency <sup>1</sup>	15.0	GHz
Power Output	25	W
Package	Surface Mount	_

#### Note:

Table 2.

Character Code	Code Value
A	0
В	1
С	2
D	3
E	4
F	5
G	6
Н	7
J	8
К	9
Examples	1A = 10.0 GHz 2H = 27.0 GHz

<sup>&</sup>lt;sup>1</sup> Alpha characters used in frequency code indicate a value greater than 9.9 GHz. See Table 2 for value.



# **Product Ordering Information**

Order Number	Description	Unit of Measure	Image
CGHV1F025S	GaN HEMT	Each	1 F 9 2 5 5
CGHV1F025-AMP1	Test board with GaN HEMT installed	Each	



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